AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Previously Presented) A method for forming a package for an electrical device, said method comprising the steps of:

attaching a removable material to a surface of conductive material before one or more isolated conductive features have been formed within said conductive material;

forming said isolated conductive features within said conductive material;

attaching encapsulant to said isolated conductive features and said removable material, wherein said attaching step is performed before a singulation process is performed to separate said package; and

removing said removable material from said conductive features and said encapsulant, wherein the removing said material step is performed after the singulation process is performed to separate said package.

2. (Original) The method for forming a package for the electronic device of claim 1, wherein said forming step includes patterning a surface of said conductive material with a material resistant to an etchant and etching said conductive material with said etchant.

3. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of forming a die attach pad within said conductive material.

4. (Previously Presented) The method for forming a package for the electronic device of claim 3, further comprising the step of coupling the device to said die attach pad.

5. (Original) The method for forming a package for an electronic device of claim 1, further comprising the step of electrically coupling an input/output portion of the device to said isolated conductive feature.

6. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of singulating individual packaged devices.

7. (Original) The method of claim 1, wherein the removable material is water soluble adhesive.

8. (Original) The method of claim 7, wherein the removable material is removed with deionized water.

9-15. (Canceled)

16. (Previously Presented) The method of claim 1, wherein the removable material is a mold stencil that is used in said attaching encapsulant step.

17. (Previously Presented) The method of claim 1, wherein said removable material comprises a polyimide material and a water soluble adhesive.

18. (Canceled)

19. (Canceled)

20. (Previously Presented) The method of claim 1, wherein said conductive material comprises a metal frame.

21. (Previously Presented) The method of claim 20, wherein the metal frame comprises a leadframe.

22. (Previously Presented) The method of claim 21, further comprising the step of forming a die attach pad within said conductive material, wherein said die attach pad is not offset from said isolated conductive features.

23. (Previously Presented) The method of claim 21, wherein a single row of connectors is formed around a perimeter of said leadframe.

24. (Previously Presented) The method of claim 20, wherein said metal frame comprises a metal sheet.

25. (Previously Presented) The method of claim 24, wherein multiple rows of connectors are formed around a perimeter of the metal sheet.

26. (Previously Presented) The method of claim 20, wherein the removable material covers substantially the entire bottom surface of said metal frame.

27. (Previously Presented) The method of claim 4, wherein the electronic device is coupled to said die attach pad via conductive epoxy.